

**Dual N-Channel MOSFET** 

### **General Description**

The WSD4064DN33 is the highest performance trench Dual N-Channel MOSFET with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The WSD4064DN33 meet the RoHS and Green Product requirement 100%  $E_{AS}$  guaranteed with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E<sub>AS</sub> Guaranteed
- Green Device Available

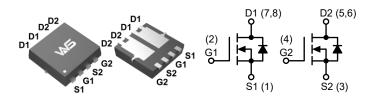
### **Product Summery**

| BV <sub>DSS</sub> | R <sub>DS(ON)</sub> | l <sub>D</sub> |  |  |
|-------------------|---------------------|----------------|--|--|
| 40V               | 19mΩ                | 13A            |  |  |

## **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### **DFN3X3-8L Pin Configuration**



### **Absolute Maximum Ratings**

| Symbol                       | Parameter                              | Parameter                 |            | Units |  |
|------------------------------|----------------------------------------|---------------------------|------------|-------|--|
| $V_{DS}$                     | Drain-Source Voltage                   |                           | 40         | V     |  |
| V <sub>GS</sub>              | Gate-Source Voltage                    | Gate-Source Voltage       |            | V     |  |
| I <sub>S</sub>               | Diode Continuous Forward Current       | T <sub>A</sub> =25°C      | 4          |       |  |
|                              | Outline and Desire Outlined            | T <sub>A</sub> =25°C      | 13         | ^     |  |
| l <sub>D</sub>               | Continuous Drain Current               | T <sub>A</sub> =70°C      | 9.5        | Α     |  |
| I <sub>DM</sub> <sup>1</sup> | Pulse Drain Current Tested             | T <sub>A</sub> =25°C      | 25         | 1     |  |
| D                            | Maximum Power Dissipation              | T <sub>A</sub> =25°C      | 2.5        | 10/   |  |
| $P_{D}$                      |                                        | T <sub>A</sub> =70°C      | 1.68       | W     |  |
| $R_{	heta JL}$               | Thermal Resistance-Junction to Lead    | Steady State              | 10         | °C/W  |  |
|                              | TI ID II II II II I                    | t≤10s                     | 42.5       | 90044 |  |
| $R_{\theta JA}$              | Thermal Resistance-Junction to Ambient | Steady State <sup>2</sup> | 50         | °C/W  |  |
| I <sub>AS</sub> <sup>3</sup> | Avalanche Current, Single pulse        | L=0.5mH                   | 10         | Α     |  |
| E <sub>AS</sub> <sup>3</sup> | Avalanche Energy, Single pulse         | L=0.5mH                   | 25         | mJ    |  |
| T <sub>STG</sub>             | Storage Temperature Range              |                           | -55 to 150 | °C    |  |
| TJ                           | Maximum Junction Temperature           |                           | 150        |       |  |

**Dual N-Channel MOSFET** 

# **Electrical Characteristics** (T<sub>J</sub>=25°C, Unless Otherwise Noted)

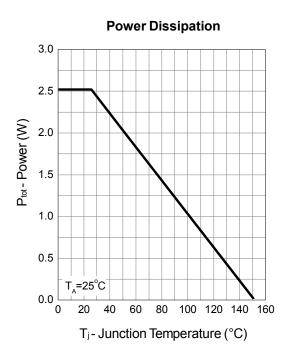
| Symbol                           | Parameter                                | Conditions                                                         | Min. | Тур. | Max. | Units |  |  |  |
|----------------------------------|------------------------------------------|--------------------------------------------------------------------|------|------|------|-------|--|--|--|
| Static Chara                     | Static Characteristics                   |                                                                    |      |      |      |       |  |  |  |
| BV <sub>DSS</sub>                | Drain-Source Breakdown Voltage           | V <sub>GS</sub> =0V , I <sub>D</sub> =250μA                        | 40   |      |      | V     |  |  |  |
|                                  | 7 0 1 1/1 5 1 0 1                        | V <sub>DS</sub> =32V , V <sub>GS</sub> =0V                         |      |      | 1.0  | - μΑ  |  |  |  |
| I <sub>DSS</sub>                 | Zero Gate Voltage Drain Current          | T <sub>J</sub> =85°C                                               |      |      | 30   |       |  |  |  |
| V <sub>GS(th)</sub>              | Gate Threshold Voltage                   | $V_{GS}=V_{DS}$ , $I_{DS}=250\mu A$                                | 1.0  | 1.5  | 2.0  | V     |  |  |  |
| I <sub>GSS</sub>                 | Gate Leakage Current                     | V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V                        |      |      | ±100 | nA    |  |  |  |
| D 4                              | Drain-Source On-state Resistance         | $V_{GS}$ =10V , $I_{D}$ =6A                                        |      | 19   | 25   | mΩ    |  |  |  |
| R <sub>DS(ON)</sub> <sup>4</sup> |                                          | V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A                         |      | 25   | 35   |       |  |  |  |
| Diode Chara                      | Diode Characteristics                    |                                                                    |      |      |      |       |  |  |  |
| V <sub>SD</sub> <sup>4</sup>     | Diode Forward Voltage                    | I <sub>SD</sub> =1A , V <sub>GS</sub> =0V                          |      | 0.75 | 1.1  | V     |  |  |  |
| t <sub>rr</sub>                  | Reverse Recovery Time                    | 1 -CA -dl /dt-100A/                                                |      | 12   |      | ns    |  |  |  |
| Q <sub>rr</sub>                  | Reverse Recovery Charge                  | - I <sub>DS</sub> =6A , dl <sub>SD</sub> /dt=100A/μs               |      | 8.5  |      | nC    |  |  |  |
| Dynamic Cha                      | aracteristics <sup>5</sup>               |                                                                    |      |      |      |       |  |  |  |
| $R_g$                            | Gate Resistance                          | V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , F = 1.0MHz             |      | 2.4  |      | Ω     |  |  |  |
| C <sub>iss</sub>                 | Input Capacitance                        |                                                                    |      | 800  |      |       |  |  |  |
| C <sub>oss</sub>                 | Output Capacitance                       | V <sub>GS</sub> =0V , V <sub>DS</sub> =20V ,<br>Frequency = 1.0MHz |      | 90   |      | pF    |  |  |  |
| C <sub>rss</sub>                 | Reverse Transfer Capacitance             |                                                                    |      | 55   |      |       |  |  |  |
| $T_{d(on)}$                      | Turn-on Delay Time                       |                                                                    |      | 7.2  |      |       |  |  |  |
| T <sub>r</sub>                   | Turn-on Rise Time                        | $V_{DD}$ =20V , $R_L$ =20 $\Omega$ , $I_{DS}$ =1A ,                |      | 6.5  |      | ns    |  |  |  |
| $T_{d(off)}$                     | Turn-off Delay Time                      | $V_{GEN}$ =10V , $R_{G}$ =6 $\Omega$                               |      | 24   |      |       |  |  |  |
| T <sub>f</sub>                   | Turn-off Fall Time                       |                                                                    |      | 4.5  |      |       |  |  |  |
| Gate Charge                      | Gate Charge Characteristics <sup>5</sup> |                                                                    |      |      |      |       |  |  |  |
| $Q_g$                            | Total Gate Charge                        | V <sub>DS</sub> =20V , V <sub>GS</sub> =10V , I <sub>DS</sub> =6A  |      | 15   | 21   |       |  |  |  |
| Qg                               | Total Gate Charge                        |                                                                    |      | 8.2  | 10   |       |  |  |  |
| Q <sub>gth</sub>                 | Threshold Gate Charge                    | \/ -20\/ \/ -45\/   -64                                            |      | 1.7  |      | nC    |  |  |  |
| Q <sub>gs</sub>                  | Gate-Source Charge                       | V <sub>DS</sub> =20V , V <sub>GS</sub> =4.5V , I <sub>DS</sub> =6A |      | 3.1  |      |       |  |  |  |
| $Q_{gd}$                         | Gate-Drain Charge                        |                                                                    |      | 2.5  |      |       |  |  |  |

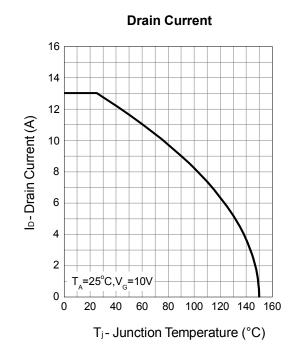
#### Note:

- 1. Pulse width limited by max. junction temperature.
- 2. Surface Mounted on 1in<sup>2</sup> pad area, t=999sec.
- 3. UIS tested and pulse width limited by maximum junction temperature 150  $^{\circ}$ C (initial temperature  $T_J$ =25  $^{\circ}$ C).
- 4. Pulse test ; pulse width≤300µs, duty cycle≤2%.
- 5. Guaranteed by design, not subject to production testing.

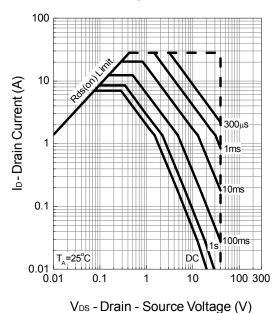


# **Typical Characteristics**

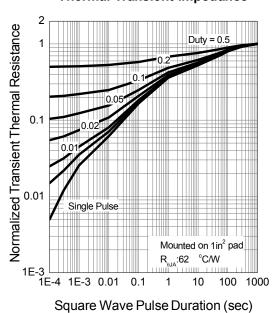




### Safe Operation Area



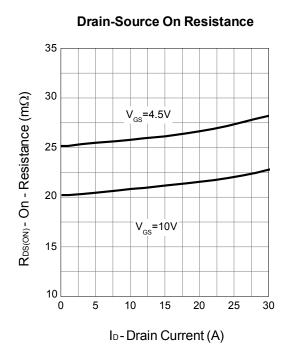
### **Thermal Transient Impedance**

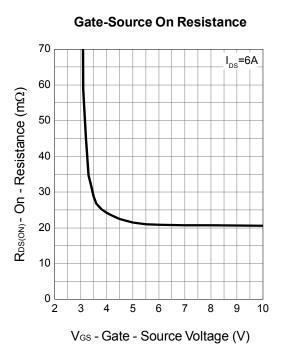


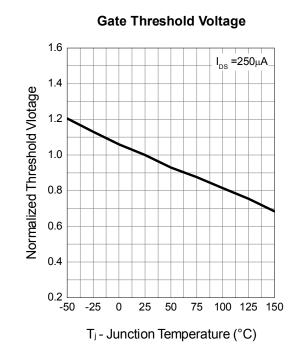


# **Typical Characteristics (Cont.)**

# **Output Characteristics** 30 =4,5,6,7,8,9,10V 25 20 Ib- Drain Current (A) 15 10 3V 5 0.0 0.5 2.5 1.0 1.5 2.0 3.0 V<sub>DS</sub> - Drain - Source Voltage (V)



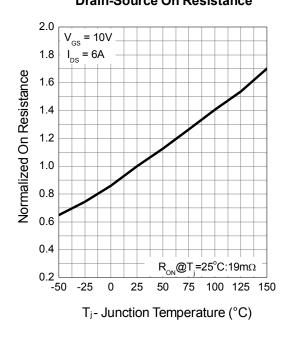




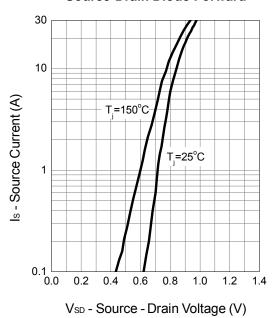


# **Typical Characteristics (Cont.)**

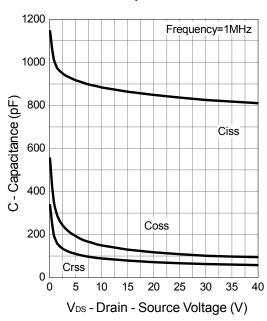
# **Drain-Source On Resistance**



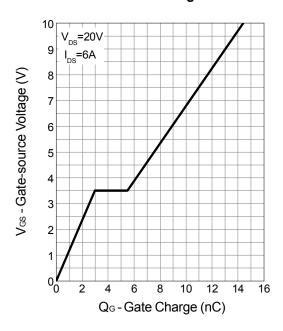
#### **Source-Drain Diode Forward**



### Capacitance

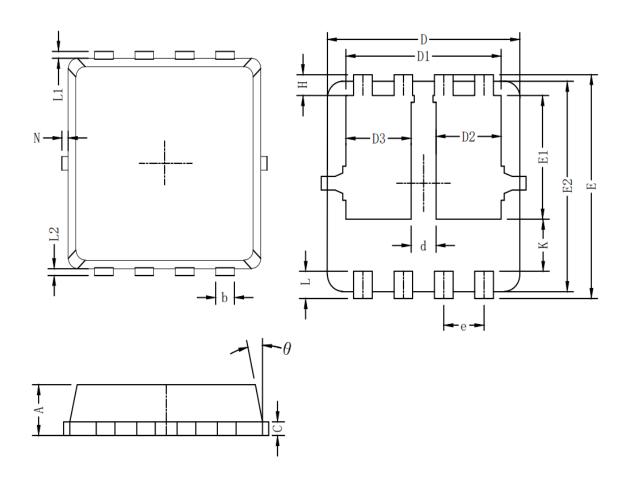


## **Gate Charge**





# **Packaging information**



| Symbol | Dim in mm |      |      |  |
|--------|-----------|------|------|--|
|        | min       | typ  | max  |  |
| А      | 0.6       | 0.75 | 0.9  |  |
| b      | 0.2       | 0.3  | 0.4  |  |
| С      | 0.15      | 0.2  | 0.25 |  |
| D      | 3         | 3.1  | 3.2  |  |
| D1     | 2.3       | 2.45 | 2.6  |  |
| D2/D3  | 0.8       | 1    | 1.2  |  |
| E      | 3.15      | 3.3  | 3.45 |  |
| E1     | 1.43      | 1.73 | 1.93 |  |
| E2     | 2.9       | 3.05 | 3.2  |  |
| е      | 0.65BSC   |      |      |  |
| Н      | 0.2       | 0.35 | 0.5  |  |
| K      | 0.57      | 0.77 | 0.87 |  |
| L      | 0.3       | 0.4  | 0.5  |  |
| L1/L2  | 0.1REF    |      |      |  |
| θ      | 8°        | 10°  | 13°  |  |
| N      | 0         |      | 0.15 |  |
| d      | 0.3       | 0.4  | 0.5  |  |



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